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Combined memory module logic devices for reduced cost and improved functionality

Abstract

An apparatus, comprising a plurality of memories and a single integrated circuit (IC) that is configured to be coupled to a host device by a host bus and that is coupled to the plurality of memories by a memory bus, wherein the IC comprises a logic buffer module that is configured to buffer data signals, command signals, address signals, and clock signals between the host device and the plurality of memories, and a power management integrated circuit (PMIC) module that is configured to regulate voltage and monitor current provided to the plurality of memories.

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Background/Summary

CROSS-REFERENCE TO RELATED APPLICATION(S) (1) The present application claims priority to U.S. Provisional Patent Application No. 63/402,432, filed Aug. 30, 2022, the disclosure of which is incorporated herein by reference in its entirety.

TECHNICAL FIELD

(1) The present disclosure generally relates to memory devices, and more particularly relates to memory devices with combined logic modules for reduced cost and improved functionality.

BACKGROUND

(2) Memory devices are widely used to store information related to various electronic devices such

as computers, wireless communication devices, cameras, digital displays, and the like. Information is stored by programming different states of a memory cell. Various types of memory devices exist, including magnetic hard disks, random access memory (RAM), read only memory (ROM), dynamic RAM (DRAM), synchronous dynamic RAM (SDRAM), and others. Memory devices may be volatile or non-volatile. Improving memory devices, generally, may include increasing memory cell density, increasing read/write speeds or otherwise reducing operational latency, increasing reliability, increasing data retention, reducing power consumption, or reducing manufacturing costs, among other metrics.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

- (1) FIG. 1 is a simplified block diagram schematically illustrating a memory device of the memory module in accordance with the embodiment of the present technology.
- (2) FIG. 2 is a simplified block diagram schematically illustrating a memory module in accordance with an embodiment of the present technology.
- (3) FIG. 3 depicts a detailed block diagram schematically illustrating the memory module shown in FIG. 2.
- (4) FIG. 4 is a simplified block diagram schematically illustrating another memory module in accordance with another embodiment of the present technology.
- (5) FIG. 5 depicts a detailed block diagram schematically illustrating the memory module shown in FIG. 4.
- (6) The drawings illustrate only example embodiments and are therefore not to be considered limiting in scope. The elements and features shown in the drawings are not necessarily to scale, emphasis instead being placed upon clearly illustrating the principles of the example embodiments. Additionally, certain dimensions or placements may be exaggerated to help visually convey such principles. In the drawings, the same reference numerals used in different embodiments designate like or corresponding, but not necessarily identical, elements.

DETAILED DESCRIPTION

- (7) Memory modules such as dual in-line memory modules (DIMM) include one or more buffers or registers between a host device and the memory device. Buffered memory modules can have improved system integration and system stability as the density of memory devices in the memory module increases while reducing electrical load on the host device. The memory buffer may be configured to transmit command signals, address signals, clock signals, data signals, power signals, or any combination thereof. For example, a load reduced DIMM (LRDIMM) has memory buffers that buffer all command, address, and clock lines to achieve a large overall maximum memory capacities, while keep the transmitting signal in parallel.
- (8) Traditional memory buffers are integrated with the memory device on the same chip as the memory array and are configured to maintain a 1:1 ratio in data speed between the host device and the memory module. That is, the host device and the memory module typically operate at a same clock frequency. Since the host device generally operates at a higher speed compared to the memory module, the on-chip memory buffer architecture limits overall system performance and challenges the system integration. In addition, a high-capacity DIMM may have a large number of memory devices, each of which receives memory address signals on the command/address bus, and their combined input buffer capacitance limits the memory module operation speed. Further, advanced memory design requires for higher memory system bandwidth and improved power efficiency while including more densified memory cells for scalability. Therefore, using a higher supply voltage to enable higher data transition rate in and out of the memory will not be a proper approach due to the increased power consumption.

(9) The memory system integration challenge and native clocking challenges of traditional memory modules require new topologies of memory architectures in achieving higher memory system bandwidth and power efficiency. The present disclosure addresses these concerns and others by providing an approach that combines memory buffer and logic functions into a single memory buffer device which is coupled to a plurality of memory devices on a memory module. In particular, the memory buffer device integrates logic buffer module(s), power management integrated circuit(s) (PMIC), and/or any other logic modules into a single semiconductor die. Moreover, migrating logic buffer and other control logic out from the memory devices provides additional silicon area on the memory devices for higher memory capacity. Further, the memory architecture presented in the present disclosure leads to a more efficient operation of the PMIC, therefore allowing a reduced memory device operating voltages and intelligent scaled output phases based on a projected memory power needs.

(10) FIG. 1 is a block diagram schematically illustrating a memory device **100** in accordance with an embodiment of the present technology. The memory device **100** may include an array of memory cells, such as memory array **150**. The memory array **150** may include a plurality of banks (e.g., banks 0-15 in the example of FIG. 1), and each bank may include a plurality of word lines (WL), a plurality of bit lines (BL), and a plurality of memory cells arranged at intersections of the word lines and the bit lines. The selection of a word line WL may be performed by a row decoder **140**, and the selection of a bit line BL may be performed by a column decoder **145**. Sense amplifiers (SAMP) may be provided for corresponding bit lines BL and connected to at least one respective local I/O line pair (LIOT/B), which may in turn be coupled to at least respective one main I/O line pair (MIOT/B), via transfer gates (TG), which can function as switches.

(11) The memory device **100** may employ a plurality of external terminals that include command and address terminals coupled to a command bus and an address bus to receive command signals CMD and address signals ADDR, respectively. The memory device may further include a chip select terminal to receive a chip select signal CS, clock terminals to receive clock signals CK and CKF, data clock terminals to receive data clock signals WCK and WCKF, data terminals DO, ROOS, DBI, and DMI, power supply terminals VDD, VSS, VDDO, and VSSO, and on-die termination terminal(s) ODT.

(12) The command terminals and address terminals may be supplied with an address signal and a bank address signal from outside. The address signal and the bank address signal supplied to the address terminals can be transferred, via a command/address input circuit **105**, to an address decoder **110**. The address decoder **110** can receive the address signals and supply a decoded row address signal (XADD) to the row decoder **140**, and a decoded column address signal (YADD) to the column decoder **145**. The address decoder **110** can also receive the bank address signal (BADO) and supply the bank address signal to both the row decoder **140** and the column decoder **145**.

(13) The command and address terminals may be supplied with command signals CMD, address signals ADDR, and chip selection signals CS, from a memory controller. The command signals may represent various memory commands from the memory controller (e.g., including access commands, which can include read commands and write commands). The select signal CS may be used to select the memory device **100** to respond to commands and addresses provided to the command and address terminals. When an active CS signal is provided to the memory device **100**, the commands and addresses can be decoded and memory operations can be performed. The command signals CMD may be provided as internal command signals ICMD to a command decoder **115** via the command/address input circuit **105**. The command decoder **115** may include circuits to decode the internal command signals ICMD to generate various internal signals and commands for performing memory operations, for example, a row command signal to select a word line and a column command signal to select a bit line. The internal command signals can also include output and input activation commands, such as clocked command CMDCK.

(14) When a read command is issued and a row address and a column address are timely supplied with the read command, read data can be read from memory cells in the memory array **150** designated by these row address and column address. The read command may be received by the command decoder **115**, which can provide internal commands to input/output circuit **160** so that read data can be output from the data terminals DO, ROOS, DBI, and DMI via read/write amplifiers **155** and the input/output circuit **160** according to the ROOS clock signals. The read data may be provided at a time defined by read latency information RL that can be programmed in the memory device **100**, for example, in a mode register (not shown in FIG. **1**). The read latency information RL can be defined in terms of clock cycles of the CK clock signal. For example, the read latency information RL can be a number of clock cycles of the CK signal after the read command is received by the memory device **100** when the associated read data is provided.

(15) When a write command is issued and a row address and a column address are timely supplied with the command, write data can be supplied to the data terminals DO, DBI, and DMI according to the WCK and WCKF clock signals. The write command may be received by the command decoder **115**, which can provide internal commands to the input/output circuit **160** so that the write data can be received by data receivers in the input/output circuit **160**, and supplied via the input/output circuit **160** and the read/write amplifiers **155** to the memory array **150**. The write data may be written in the memory cell designated by the row address and the column address. The write data may be provided to the data terminals at a time that is defined by write latency WL information. The write latency WL information can be programmed in the memory device **100**, for example, in the mode register (not shown in FIG. **1**). The write latency WL information can be defined in terms of clock cycles of the CK clock signal. For example, the write latency information WL can be a number of clock cycles of the CK signal after the write command is received by the memory device **100** when the associated write data is received.

(16) The power supply terminals may be supplied with power supply potentials VDD and VSS. These power supply potentials VDD and VSS can be supplied to an internal voltage generator circuit **170**. The internal voltage generator circuit **170** can generate various internal potentials VPP, VOD, VARY, VPERI, and the like based on the power supply potentials VDD and VSS. The internal potential VPP can be used in the row decoder **140**, the internal potentials VOD and VARY can be used in the sense amplifiers included in the memory array **150**, and the internal potential VPERI can be used in many other circuit blocks.

(17) The power supply terminal may also be supplied with power supply potential VDDQ. The power supply potential VDDQ can be supplied to the input/output circuit **160** together with the power supply potential VSS. The power supply potential VDDQ can be the same potential as the power supply potential VDD in an embodiment of the present technology. The power supply potential VDDQ can be a different potential from the power supply potential VDD in another embodiment of the present technology. However, the dedicated power supply potential VDDQ can be used for the input/output circuit **160** so that power supply noise generated by the input/output circuit **160** does not propagate to the other circuit blocks.

(18) The on-die termination terminal(s) may be supplied with an on-die termination signal ODT. The on-die termination signal ODT can be supplied to the input/output circuit **160** to instruct the memory device **100** to enter an on-die termination mode (e.g., to provide one of a predetermined number of impedance levels at one or more of the other terminals of the memory device **100**).

(19) The clock terminals and data clock terminals may be supplied with external clock signals and complementary external clock signals. The external clock signals CK, CKF, WCK, WCKF can be supplied to a clock input circuit **120**. The CK and CKF signals can be complementary, and the WCK and WCKF signals can also be complementary.

(20) Complementary clock signals can have opposite clock levels and transition between the opposite clock levels at the same time. For example, when a clock signal is at a low clock level a complementary clock signal is at a high level, and when the clock signal is at a high clock level the

complementary clock signal is at a low clock level. Moreover, when the clock signal transitions from the low clock level to the high clock level the complementary clock signal transitions from the high clock level to the low clock level, and when the clock signal transitions from the high clock level to the low clock level the complementary clock signal transitions from the low clock level to the high clock level.

(21) Input buffers included in the clock input circuit **120** can receive the external clock signals. For example, when enabled by a CKE signal from the command decoder **115**, an input buffer can receive the CK and CKF signals and the WCK and WCKF signals. The clock input circuit **120** can receive the external clock signals to generate internal clock signals ICLK. The internal clock signals ICLK can be supplied to an internal clock circuit **130**. The internal clock circuit **130** can provide various phase and frequency controlled internal clock signal based on the received internal clock signals ICLK and a clock enable signal CKE from the command/address input circuit **105**. For example, the internal clock circuit **130** can include a clock path (not shown in FIG. **1**) that receives the internal clock signal ICLK and provides various clock signals to the command decoder **115**. The internal clock circuit **130** can further provide input/output (I/O) clock signals. The I/O clock signals can be supplied to the input/output circuit **160** and can be used as a timing signal for determining an output timing of read data and the input timing of write data. The I/O clock signals can be provided at multiple clock frequencies so that data can be output from and input to the memory device **100** at different data rates. A higher clock frequency may be desirable when high memory speed is desired. A lower clock frequency may be desirable when lower power consumption is desired. The internal clock signals ICLK can also be supplied to a timing generator **135** and thus various internal clock signals can be generated.

(22) Turning to FIG. **2**, a memory module **220** is illustrated in accordance with one embodiment of the present technology. The memory module **220** is coupled with a host device **210** through a host bus **230**. Particularly, the memory module **220** includes a plurality of memory devices **250** and a memory buffer integrated circuit (IC) **240**, the memory devices **250** and the memory buffer IC **240** being operably coupled by a memory bus **260**.

(23) In an exemplary embodiment, the memory buffer IC **240** includes memory buffers that receive signals including command, address, power, or clock signals from the host device **210** through the host bus **230**. The memory buffer IC **240** then distributes and/or re-transmits the received signals to the plurality of memory devices **250** over the memory bus **260**. In one embodiment, the memory buffer IC **240** permits configurability of memory bus width and clock speed. For example, the memory buffer IC **240** can be configured to provide a wider memory bus width and a slower clock speed between the host device **210** and the plurality of memory devices **250**. In another example, the memory buffer IC **240** can be configured to provide a narrower memory bus width and a faster clock speed between the host device **210** and the plurality of memory devices **250**.

(24) In another exemplary embodiment, the host device **210** transmits command/address signals to, and receives data signals from, the memory module **220** during memory access operations (e.g., reads and writes). The host device **210** can be any one of a number of electronic devices capable of utilizing memory for the temporary or persistent storage of information, or a component thereof. For example, the host device **210** may be a computing device such as a desktop or portable computer, a server, a hand-held device (e.g., a mobile phone, a tablet, a digital reader, a digital media player), or some component thereof (e.g., a central processing unit, a co-processor, a dedicated memory controller, etc.). The host device **210** may be a networking device (e.g., a switch, a router, etc.) or a recorder of digital images, audio and/or video, a vehicle, an appliance, a toy, or any one of a number of other products. In one embodiment, the host device **210** may be indirectly connected to the memory module **220** (e.g., over a networked connection or through intermediary devices).

(25) In another exemplary embodiment, the plurality of memory devices **250** each include one or more memory arrays that are operably coupled to the memory buffer IC **240**. For example, the

memory devices **250** can each include an array of memory cells, including volatile (e.g., DRAM, SRAM, floating body RAM, etc.) and/or non-volatile (NAND, NOR, 3D XPoint™, PCM, MRAM, FeRAM, etc.) cells. In one embodiment, the memory devices **250** and the memory buffer IC **240** can be fabricated on separated semiconductor dice and packaged in a same assembly. In another embodiment, the memory devices **250** and the memory buffer IC **240** can be packaged in separate assemblies and interconnected on a same printed circuit board (PCB). In this example, the memory buffer IC **240** is shown schematically in FIG. 2 in a single block, but it can also be provided in separate functional blocks, which can be included in a single assembly.

(26) In another exemplary embodiment, the memory buffer IC **240** includes a PMIC module to convert a supply voltage to one or more output voltages (e.g., VDD, VDDQ, VPP, VSSQ, etc.) for use by the memory device **250**. In this regard, the output voltage generated by the PMIC module of the memory buffer IC **240** can have a different voltage level (e.g., 1.1V, 1.3V, 1.5V, etc.) than that of the supply voltage (e.g., 3.3V, 5V, 12V, etc.) with a different tolerance (e.g., $\pm 1\%$, $\pm 3\%$, $\pm 5\%$, etc.) than that of the supply voltage (e.g., $\pm 5\%$, $\pm 10\%$, etc.). Further, the memory buffer IC **240** can also operate the PMIC module to further supply output voltage to an output contact edge connector of a packaged memory module **220** to enable the memory module **220** to provide converted and/or regulated output voltage to one or more device external to the memory module **220** (e.g., another memory module without a PMIC module, a processor, a chipset, another logic circuit, an expansion card, etc.).

(27) FIG. 3 depicts a detailed block diagram of the memory module illustrated in FIG. 2. In this example, the memory devices **250** can each include an array of memory cells, including volatile and/or non-volatile cells. In one embodiment, the memory devices **250** and the memory buffer IC **240** are each provided as separate semiconductor chips (e.g., separately connected to the memory module **220**).

(28) In one embodiment, the host device **210** may include one or more processors, such as a general-purpose processor **212**, a central processing unit (CPU) **214**, or an application processor **216**, which are coupled to the memory module **220** by the host bus **230**. The host bus **230** receives command or address signals, clock signals, power signals, and data signals from, and transmits data signals to one or more of the processors during memory access operations (e.g., reads and writes). In one embodiment, the one or more processors may be connected directly to the memory buffer IC **240** of the memory module **220** for signals transitions. In other embodiments, the one or more of the processors may be indirectly connected to the memory buffer IC **240** (e.g., over a networked connection or through intermediate devices).

(29) In one embodiment, the memory devices **250** can include a double data rate (DDR) SDRAM with two independent subchannels, e.g., when the memory module **220** is a dual in-line memory module (DIMM). Each subchannel of the memory devices **250** can have up to two or more physical memory package ranks. Each of the two memory package ranks can be configured in a primary/secondary topology to enable additional logical ranks for increased memory density. Here, the local voltage regulation of the memory device **250** is performed by the PMIC module **244** provided in the memory buffer IC **240** through the memory bus **260**.

(30) In one embodiment, the memory buffer IC **240** includes a logic buffer **242** that is connected to the host device **210** through the host bus **230** and that is coupled to the memory devices **250** through the memory bus **260**. The logic buffer **242** may receive command and/or address signals and data signals via the host bus **230** and transmit the signals to the memory devices **250** to perform memory operations. The memory devices **250** can also return data signals, such as read data or write confirmation information to the host device **210** via the logic buffer **242**. In one embodiment, the logic buffer **242** is configured to receive signals from the host that are encoded according to a first communication protocol, and to convert/encode the signals according to a second communication protocol before providing them to the memory devices **250**, and vice versa. The communication protocols may be associated with a particular type of memory device, such as

DDR5, LPDDR5, SERDES, etc. In some embodiments, the signal sent to the memory devices **250** may be a multilevel signal. For example, two bits encoded as a single voltage level corresponding to a logical state of the two bits (e.g., logic 00, 01, 10, or 11 etc.). Other types of multilevel signals may also be used. Through translating the signals received on one bus before transmitting them on the other, the logic buffer **242** enables the host device **210** to communicate with the memory devices **250** using various communication protocols. In some other embodiments, the logic buffer **242** could enable a first-in, first-out (FIFO) buffering, by which the order in which the data enters the memory buffer IC **240** and transits out to the memory device **250** is maintained in a same sequence. In other embodiments, the logic buffer **242** could enable an out-of-order buffering or an opposite-order buffering, e.g., a last-in, first-out (LIFO) buffering, by which the received data from the host device **210** is transmitted to the memory devices **250** in the opposite order than that in which it was received by the memory buffer IC **240**.

(31) In one embodiment, the memory buffer IC **240** may also include a PMIC module **244**. According to one embodiment of the subject technology, the PMIC module **244** can include one or more registers for storing information of output voltage to the operably connected memory device **250**. For example, the PMIC registers may include information corresponding to the voltage levels of the output voltages, tolerances of the output voltages, and order in which the output voltages are powered up and/or powered down, delays between powering up/down the output voltages, etc. In some embodiments, the PMIC module **244** can be configured to output information or a portion thereof in response to a command received by the memory module **220** from the connected host device **210**. For example, the application processor **216** of the host device **210** can issue a command signal to the memory module **220** to cause a changed output voltage level for the memory devices **250**. In response, the PMIC module **244** combined in the memory buffer IC **240** can modify its voltage level in accordance with the modified information in its PMIC registers and transmits the modified output voltage to the memory device **250** through the memory bus **260**. In one embodiment, the PMIC module **244** can be configured to perform smart voltage regulation on the memory device **250**. For example, the PMIC module **244** can provide power signals to the memory arrays of the memory devices **250** to enable configurability of voltage ramps and levels as well as current monitoring. Here, the power management on memory device **250** can be performed from a remote chip, i.e., the memory buffer IC **240**, to allow additional power management functions like threshold protection, error injection capabilities, and programmable power on sequence, etc. The presence of the PMIC module **244** on a separate memory buffer chip (e.g., the memory buffer IC **240**) enables better power regulation and reduces complexity of the memory device design by reducing a scope of DRAM power delivery network management.

(32) In one embodiment, the PMIC module **244** could enable a dynamic supply voltage scaling on the memory devices **250**. Since the PMIC module **244** can be integrated on the memory buffer IC **240** with a logic buffer which monitors status of the coupled memory devices **250**, it can be configured to reduce or increase the supply voltage to the memory devices **250** when it is safe.

(33) In one embodiment, the memory buffer IC **240** may include a serial presence detect (SPD) hub **246**. The SPD hub **246** can perform as a secondary to the memory device system host sideband and act as a primary to the remaining active components. The SPD hub **246** may contain programmable read-only memory (PROM) pertaining to the SPD. In one embodiment, the SPD hub **246** interacts with the host device **210** via the host bus **230**, and decouples the load transmitted from the host device **210** to the memory devices **250**, while providing local access to remaining components of the memory buffer IC **240** including the logic buffer **242**, PMIC module **244**, and a temperature sensor module **248**. In this example, features of the SPD hub **246** allows an isolation of internal memory buses within memory devices **250** from the host bus **230**.

(34) In one embodiment, the memory buffer IC **240** may include a temperature control module **248** configured to sense local temperatures on the memory devices **250**. For example, one or more temperature sensors can be embedded in the memory banks of the memory devices **250** to monitor

thermal changes across the length of each memory subchannel. Particularly, each temperature sensor can be placed strategically near each end of the memory banks (e.g., corresponding to DIMM subchannels). Here, the temperature sensor module **248** may be connected with the temperature sensors via a I2C/I3C bus that is incorporated in the memory bus **260**. The temperature control module **248** communicates with the embedded temperature sensor to monitor temperature update flags from each DRAM die of the memory package banks until a temperature threshold is approaching. The temperature control module **248** may be an analog device or a mixed-signal device for receiving temperature control signals from or outputting the memory device temperature information to the host device **210**.

(35) In another embodiment, the memory buffer IC **240** may include a temperature control module **248** that configured for module-level or logic-level temperature monitoring. For example, one or more temperature sensors can be embedded on the memory module **220**, e.g., on the memory buffer IC **240** or on one of the memory devices **250**. The temperature control module **248** may be connected with the embedded one or more temperature sensors to monitor the temperature of the memory module **220**. In another embodiment, the one or more temperature sensors may be disposed within the temperature control module **248** for the module-level temperature monitoring.

(36) In some embodiments, the memory buffer IC **240** may also include security logic modules, e.g., enhanced SPD functions with logic for memory module authentication. In other embodiments, the memory buffer IC **240** may include a secure buffer ASIC module to provide privacy guarantees for data and computation in the memory module **220**. For example, RAM controller functionality can be shifted from a secure CPU to the secure buffer module of the memory buffer IC **240**. This way, a CPU vendor can design its own trusted buffer memory chip and secure the memory devices **250** while using non-trusted commodity DRAM chips.

(37) In some embodiments, various components of the memory buffer IC **240** including the logic buffer **242**, the PMIC module **244**, the SPD hub **246**, and the temperature sensor module **248**, can all be fabricated by a conventional semiconductor process, e.g., a fin field-effect transistor (FinFET) process and integrated on a same memory buffer chip. Components of the memory buffer IC **240** can also be fabricated on separated semiconductor dice and packaged into an individual memory buffer assembly.

(38) Turning to FIG. 4, a simplified block diagram schematically illustrating another memory module **320** in accordance with another embodiment of the present technology. In this example, the memory module **320** is coupled with a host device **310** through a host bus **330**. The memory module **320** includes a plurality of memory devices **350** designated as multiple channels. In addition, the memory module **320** includes a plurality of memory buffer integrated circuits (ICs) **340** including memory buffer IC **340a** and memory buffer IC **340b**. The memory buffer ICs **340a** and **340b** are configured to transmit signals including command signals, address signals, power signals, clock signals and data signals between the host device **310** and the plurality of memory devices **350** through the host bus **330** and a plurality of memory buses including memory bus **360a** and memory bus **360b**. This memory architecture enables memory buffer and logic functions to be done on a memory channel basis, i.e., one of the memory buffer ICs being coupled to one of the multiple memory channels.

(39) In one embodiment, the host device **310** perform memory operations such as memory read and write on a different channel of the memory channels populated by a different set of memory devices **350**. Specifically, the memory channel operation can be conducted through one of the memory buffer ICs **340**. For example, the memory buffer IC **340a** receives command/address signals that are dedicated to a first memory module channel and transmits the signals to the memory devices **350** of the first memory module channel. On the other hand, the memory buffer IC **340a** reads data from the memory devices **350** of the first memory channel and transmits the data signal to the host device **310**. In this example, the memory buffer IC **340a** is coupled with the first memory channel by the memory bus **360a**. Similarly, the memory buffer IC **340b** can be

configured to receive command/address signals from the host device **310** and data signals from memory devices **350** of a second memory channel, and to transmit the command/address signals and the data signals to the memory devices **350** of the second memory channel and the host device **310**, respectively. In this example, the number of memory buffer chips are equal to or more than the number of memory channels of the memory module **320**. This way, at least one memory buffer chip can be designated for buffering data signals and logic control signals between the host device **310** and one memory channel.

(40) In one embodiment, the memory module **320** enables memory device power savings by enabling the PMIC functions on a per-memory channel basis. For example, multiple PMIC modules included in the memory buffer ICs **340a** and **340b** can be dedicated/coupled to memory channels of the memory module **320**, so as to reduce power supply voltage to one of the memory channels while maintaining a higher supply voltage to other memory channels of the memory module **320**. The memory architecture shown in FIG. **4**, specifically migrating the PMIC modules to the plurality of memory buffer ICs, independently manages power supply on each of the memory channels according to each of the memory channels' operations.

(41) FIG. **5** depicts a detail block diagram of the memory module **320** illustrated in FIG. **4**. In this example, the memory module **320** includes a plurality of memory buffer ICs **340**, each of the memory buffer ICs **340** being dedicated to a memory channel of the memory module **320** for memory buffering and logic controls.

(42) In one embodiment, the host device **310** may include one or more processors, such as a general-purpose processor **312**, a central processing unit **314**, or an application processor **316**, which are coupled to the memory module **320** by the host bus **330**. The host bus **330** receives command or address signals, clock signal, power signal, and data signals from, and transmits data signals to one or more of the processors during memory access operations (e.g., reads and writes). In one embodiment, the one or more processors may be connected directly to the memory buffer ICs of the memory module **320** for signals transition. In other embodiments, the one or more of the processors may be indirectly connected to the memory module **320** (e.g., over a networked connection or through intermediate devices).

(43) In one embodiment, the memory module **320** may include multiple ranks/independent channels of memory devices **350**, e.g., the memory channel **370a** and memory channel **370b**. Each channel of the memory module **320** may be configured to include a plurality of memory devices. For example, each of the memory channels **370a** and **370b** includes five memory devices **350**. Here, each memory channel can be configured to include four memory devices that are dedicated for storing user data, with a fifth memory device that is dedicated for storing metadata about the user data for error detection and/or correction. Alternatively, all five memory devices **350** of each of the memory channels can be similarly configured to operate with multiple pseudo-channels, such that all of the memory devices **250** being configured to store metadata.

(44) In one embodiment, the memory module **320** includes a plurality of memory buffer ICs. For example, memory buffer IC **340a** and **340b** are included in the memory module **320** and are coupled to the memory channels **370a** and **370b** through the memory bus **360a** and **360b**, respectively. In particular, each of the memory buffer ICs **340** is coupled to a different memory channel of the memory module **320** populated by a different set of memory devices **350**. For example, the memory buffer IC **340a** is coupled to the memory channel **370a**, buffering signals and providing logic controls to the five memory devices **350** of the memory channel **370a**. Similarly, the memory buffer IC **340b** is couple to the memory channel **370b**, buffering signals and providing logic controls to the five memory devices **350** of the memory channel **370b**.

(45) In one embodiment, each of the plurality of memory buffer ICs is an individually packaged chip that combines various functional modules including a logic buffer, a PMIC module, a SPD hub, and a temperature control module. For example, the memory buffer IC **340a** includes a logic buffer module **342a** configured to transmit command/address signals received from the host device

310 to the memory subchannel **350a** of the memory device **350**. In turn, the logic buffer **342a** transmits data signals from the memory channel **370a** to the host device **310**. In this example, the memory buffer IC **340a** also include a PMIC module **344b** that is configured for voltage regulation on the memory device of memory channel **370a**. Specifically, the PMIC module **344b** may perform a specific voltage control on the memory devices of memory channel **370a** that are different to other memory devices of the memory module **320**. Further, the memory buffer IC **340a** may include a SPD hub **246a** that is dedicated to the operation of memory channel **370a** and that provides local access to remaining components of the memory buffer IC **340A** such as the logic buffer **342a**, the PMIC module **344a**, and temperature control module **348a**. In this example, the memory buffer IC **340a** may include a temperature control module **348a** configured to sense local temperature of the memory devices in the memory channels. One or more temperature sensors may be embedded in the memory channels of the memory module **320** to detect thermal changes across the length of the memory channel. The temperature control module **348a** communicates with the one or more temperature sensors via the memory bus **360a** to update flags from each memory device **350** of the memory channel **370a** until a temperature threshold is approaching. In another embodiment, the temperature control module **348a** may be configured to monitor module-level or logic-level temperature by embedding one or more temperature sensors on the memory module **220**, e.g., on the memory buffer IC **340a**.

(46) In one embodiment and similar to the memory buffer IC **340a**, the memory buffer IC **340b** includes a logic buffer **342b**, a PMIC module **344b**, a SPD hub **346b**, and a temperature sensor module **348b** that are configured to transmit data signals and logic control signals between the host device **310** and memory devices **350** of the memory channel **370b**. The transition of data signals and control signals there between is conducted through the memory bus **360b**.

(47) In one embodiment, each component of the memory buffer ICs **340** are fabricated by a conventional semiconductor process, e.g., a FinFET process that the memory buffer IC components can be fabricated on a same die and packaged into an individual memory buffer assembly. In this example, the memory buffer ICs **340a** and **340b**, as well as the memory channels can be incorporated on a PCB to form the memory module **320**.

(48) It should be noted that the methods described above describe possible implementations, and that the operations and the steps may be rearranged or otherwise modified and that other implementations are possible. Furthermore, embodiments from two or more of the methods may be combined.

(49) Specific details of several embodiments of semiconductor devices, and associated systems and methods, are described below. A person skilled in the relevant art will recognize that suitable stages of the methods described herein can be performed at the wafer level or at the die level. Therefore, depending upon the context in which it is used, the term “substrate” can refer to a wafer-level substrate or to a singulated, die-level substrate. Furthermore, unless the context indicates otherwise, structures disclosed herein can be formed using conventional semiconductor-manufacturing techniques. Materials can be deposited, for example, using chemical vapor deposition, physical vapor deposition, atomic layer deposition, plating, electroless plating, spin coating, and/or other suitable techniques. Similarly, materials can be removed, for example, using plasma etching, wet etching, chemical-mechanical planarization, or other suitable techniques.

(50) Information and signals described herein may be represented using any of a variety of different technologies and techniques. For example, data, instructions, commands, information, signals, bits, symbols, and chips that may be referenced throughout the above description may be represented by voltages, currents, electromagnetic waves, magnetic fields or particles, optical fields or particles, or any combination thereof. Some drawings may illustrate signals as a single signal; however, it will be understood by a person of ordinary skill in the art that the signal may represent a bus of signals, where the bus may have a variety of bit widths.

(51) The devices discussed herein, including a memory device, may be formed on a semiconductor

substrate or die, such as silicon, germanium, silicon-germanium alloy, gallium arsenide, gallium nitride, etc. In some cases, the substrate is a semiconductor wafer. In other cases, the substrate may be a silicon-on-insulator (SOI) substrate, such as silicon-on-glass (SOG) or silicon-on-sapphire (SOP), or epitaxial layers of semiconductor materials on another substrate. The conductivity of the substrate, or sub-regions of the substrate, may be controlled through doping using various chemical species including, but not limited to, phosphorous, boron, or arsenic. Doping may be performed during the initial formation or growth of the substrate, by ion-implantation, or by any other doping means.

(52) The functions described herein may be implemented in hardware, software executed by a processor, firmware, or any combination thereof. Other examples and implementations are within the scope of the disclosure and appended claims. Features implementing functions may also be physically located at various positions, including being distributed such that portions of functions are implemented at different physical locations.

(53) As used herein, including in the claims, “or” as used in a list of items (for example, a list of items prefaced by a phrase such as “at least one of” or “one or more of”) indicates an inclusive list such that, for example, a list of at least one of A, B, or C means A or B or C or AB or AC or BC or ABC (i.e., A and B and C). Also, as used herein, the phrase “based on” shall not be construed as a reference to a closed set of conditions. For example, an exemplary step that is described as “based on condition A” may be based on both a condition A and a condition B without departing from the scope of the present disclosure. In other words, as used herein, the phrase “based on” shall be construed in the same manner as the phrase “based at least in part on.”

(54) As used herein, the terms “over,” “up,” “down,” and “below” can refer to relative directions or positions of features in the semiconductor devices in view of the orientation shown in the Figures. These terms, however, should be construed broadly to include semiconductor devices having other orientations, such as inverted or inclined orientations where top/bottom, over/under, above/below, up/down, and left/right can be interchanged depending on the orientation.

(55) From the foregoing, it will be appreciated that specific embodiments of the invention have been described herein for purposes of illustration, but that various modifications may be made without deviating from the scope of the invention. Rather, in the foregoing description, numerous specific details are discussed to provide a thorough and enabling description for embodiments of the present technology. One skilled in the relevant art, however, will recognize that the disclosure can be practiced without one or more of the specific details. In other instances, well-known structures or operations often associated with memory systems and devices are not shown, or are not described in detail, to avoid obscuring other aspects of the technology. In general, it should be understood that various other devices, systems, and methods in addition to those specific embodiments disclosed herein may be within the scope of the present technology.

Claims

1. An apparatus, comprising: a plurality of memories; and a single integrated circuit (IC) that is configured to be coupled to a host device by a host bus and that is coupled to the plurality of memories by a memory bus, wherein the IC comprises: a logic buffer module that is configured to buffer data signals, command signals, address signals, and clock signals between the host device and the plurality of memories and to monitor a status of the plurality of memories, and a power management integrated circuit (PMIC) module that is coupled with the logic buffer module, wherein the PMIC is configured, based on the monitored status of the plurality of memories, to enable a dynamic supply voltage scaling for the plurality of memories.
2. The apparatus of claim 1, wherein the plurality of memories comprises double data rate synchronous dynamic random-access memories.
3. The apparatus of claim 1, wherein the PMIC module is further configured to enable threshold

voltage protection, programmable power on sequence, or power management to the plurality of memories.

4. The apparatus of claim 1, wherein the PMIC module is further configured to regulate voltage and monitor current provided to the plurality of memories.

5. The apparatus of claim 1, wherein the single IC further comprises a serial presence detect (SPD) hub that is configured to control plane communication between components of the IC and the host device, and to decouple load from the host device to the plurality of memories.

6. The apparatus of claim 1, wherein the single IC further comprises a temperature control module.

7. The apparatus of claim 1, wherein the single IC further comprises a security logic module.

8. The apparatus of claim 1, wherein the single IC is configured to support multi-level signaling between the host device and the plurality of memories.

9. The apparatus of claim 1, wherein the single IC is configured to support various buffering operations including First-In-First-Out (FIFO), Last-In-First-Out (LIFO), or out-of-order execution.

10. The apparatus of claim 1, wherein the logic buffer of the single IC permits configurability of memory bus width and clock speed.

11. A memory system, comprising: a host device; a memory module including: a first plurality of memory devices, and a first single integrated circuit (IC) coupled to the first plurality of memory devices by a first memory bus, wherein the first single IC comprises: a first logic buffer module that is configured to buffer data signals, command signals, address signals, and clock signals between the host device and the first plurality of memory devices and to monitor a status of the first plurality of memories, and a first power management integrated circuit (PMIC) module that is coupled with the first logic buffer module, wherein the first PMIC is configured, based on the monitored status of the first plurality of memory devices, to enable a first dynamic supply voltage scaling for the first plurality of memory devices; and a host bus that is configured to couple the host device and the memory module.

12. The memory system of claim 11, wherein the memory module further comprises: a second plurality of memory devices, and a second single IC coupled to the second plurality of memory devices by a second memory bus, wherein the second single IC comprises: a second logic buffer module that is configured to buffer data signals, command signals, address signals, and clock signals between the host device and the second plurality of memory devices and to monitor a status of the second plurality of memories, and a second PMIC module that is coupled with the second logic buffer module, wherein the second PMIC is configured, based on the monitored status of the second plurality of memory devices, to enable a second dynamic supply voltage scaling for the second plurality of memory devices.

13. The memory system of claim 12, wherein each of the first and second single ICs further comprises a temperature control module.

14. The memory system of claim 12, wherein each of the first and second single ICs further comprises a serial presence detect (SPD) hub that is configured to control plane communication between components of the IC and the host device, and to decouple load from the host device to the memory module.

15. The memory system of claim 12, wherein each of the first and second single ICs further comprises a security logic module.

16. The memory system of claim 12, wherein the PMIC module of each of the first and second single ICs is configured to enable threshold voltage protection, programmable power on sequence, or power management to the first and second plurality of memory devices, respectively.

17. The memory system of claim 11, wherein the memory module comprises double data rate synchronous dynamic random-access memories.

18. An integrated circuit (IC), comprising: a logic buffer module that is configured to buffer data signals, command signals, address signals, and clock signals between a host device and one or more corresponding memory channels of a memory module and to monitor a status of the memory

module; a power management integrated circuit (PMIC) module that is coupled with the logic buffer module, wherein the PMIC is configured, based on the monitored status of the memory module, to enable a dynamic supply voltage scaling for the memory module; memory bus terminals that are configured to be coupled to the one or more memory channels; and host bus terminals that are configured to be coupled to the host device.

19. The integrated circuit of claim 18, further comprises a serial presence detect (SPD) hub that is configured to control plane communication between components of the IC and the host device, and to decouple load from the host device to the corresponding one or more memory channels of the memory module.

20. The integrated circuit of claim 18, further comprising a temperature control module and a security logic module.
